

Electronic Patent Application Fee Transmittal

Application Number:	10755042			
Filing Date:	09-Jan-2004			
Title of Invention:	Integrated chip package structure using silicon substrate and method of manufacturing the same			
First Named Inventor/Applicant Name:	Mou-Shiung Lin			
Filer:	Dennis Alan Duchene/ShirLynn Mata			
Attorney Docket Number:	085027-0104			
Filed as Large Entity				
Utility under 35 USC 111(a) Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180